	Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
			* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-11-16
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

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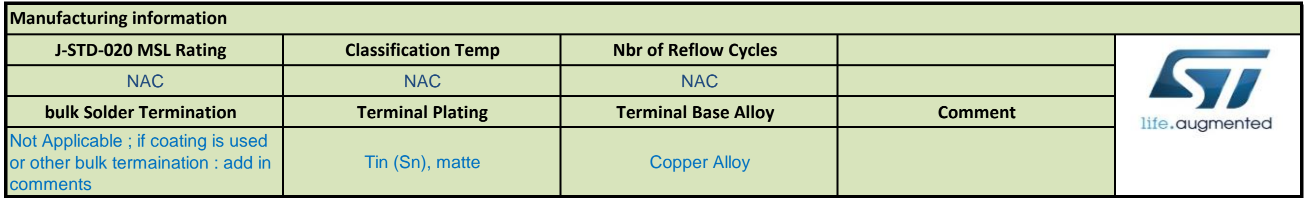
Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM8S105K4B6	V176*766XXXX	A	998G	2015-11-16
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	4070.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
NAC	NAC	NAC		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	28,8.89,3.80	32	gull wing	
Comment	Package: 76 PDIP 32 .4 Cu .25 Shrink 0123183			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-15th June 2015				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	V176*766XXXX					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or Dies	Other inorganic materials	4.517	mg	supplier	die	Silicon (Si)	7440-21-3		4.364	mg	966128	1072
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	2657	3
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0.040	mg	8855	10
Die or Dies				supplier	metallization	Tantalum (Ta)	7440-25-7		0.019	mg	4206	5
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1328	1
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.011	mg	2435	3
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.065	mg	14390	16
Leadframe(Full River, SDIP32B)	Other inorganic materials	1639.030	mg	Supplier	Alloy	Copper(CU)	7440-50-8		1596.792	mg	974230	392332
Leadframe(Full River, SDIP32B)				Supplier	Alloy	Phosphorus(P)	7723-14-0		1.344	mg	820	330
Leadframe(Full River, SDIP32B)				Supplier	Alloy	Iron(Fe)	7439-89-6		38.517	mg	23500	9464
Leadframe(Full River, SDIP32B)				Supplier	Alloy	Zinc(Zn)	7440-66-6		2.049	mg	1250	503
Leadframe(Full River, SDIP32B)				Supplier	Alloy	Lead(Pb)	7439-92-1		0.328	mg	200	81
Die Attach(Sumitomo, CRM-1033BF)	Other inorganic materials	0.601	mg	Supplier	Glue	Silver(Ag)	7440-22-4		0.421	mg	700499	103
Die Attach(Sumitomo, CRM-1033BF)				Supplier	Glue	Epoxy Resin	9003-36-5		0.120	mg	199667	29
Die Attach(Sumitomo, CRM-1033BF)				Supplier	Glue	t-Butyl pheny1 glycidyl ether	3101-60-8		0.048	mg	79867	12
Die Attach(Sumitomo, CRM-1033BF)				Supplier	Glue	Phenolic resin	92-88-6		0.006	mg	9983	1
Die Attach(Sumitomo, CRM-1033BF)				Supplier	Glue	Butyl cellosolve acetate	112-07-2		0.006	mg	9983	1
Bonding wire(Heraeus, 1mil Au)	Other inorganic materials	1.005	mg	Supplier	Bonding wire	Gold(Au)	7440-57-5		1.005	mg	1000000	247
Encapsulation(Samsung, SG8300SY)	Other inorganic materials	2410.847	mg	Supplier	Molding compound	Silica Fused	60676-86-0		2090.184	mg	866992	513559
Encapsulation(Samsung, SG8300SY)				Supplier	Molding compound	Epoxy Resin	NA		192.880	mg	80005	47391
Encapsulation(Samsung, SG8300SY)				Supplier	Molding compound	Phenol Resin	NA		120.550	mg	50003	29619
Encapsulation(Samsung, SG8300SY)				Supplier	Molding compound	Carbon Black	1333-86-4		7.233	mg	3000	1777
Finishing(Yunnan Tin)	Other inorganic materials	14.000	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		14.000	mg	1000000	3440